



OLED SPECIFICATION

Model No:

REX012832AWPP3N00000

CUSTOMER:

| APPROVED BY | |
|-------------|--|
| PCB VERSION | |
| DATE | |

FOR CUSTOMER USE ONLY

| SALES BY | APPROVED BY | CHECKED BY | PREPARED BY |
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APPROVAL FOR SPECIFICATIONS ONLY

 \square APPROVAL FOR SPECIFICATIONS AND SAMPLE



1. Revision History

| VERSION | DATE | REVISED PAGE NO. | Note |
|---------|------------|------------------|-------------------------|
| 0 | 2015/07/24 | | First release |
| Α | 2015/12/07 | | Modify Life Time |
| В | 2016/06/01 | | Modify Static |
| | | | electricity test |
| С | 2017/10/30 | | Modify Reliability test |
| | | | Condition |



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- 1.General Specification
- 2. Module Classification Information
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- 4. Contour Drawing & Block Diagram
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- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of OLED Modules



1.General Specification

The Features is described as follow:

■ Module dimension: 62.0 × 24.0 × 2.35 (MAX) mm

■ View area: 57.02 x 15.10 mm

■ Active area: 55.018 x 13.098 mm

■ Dot Matrix: 128*32

Dot size: 0.408 × 0.388 mm
 Dot pitch: 0.43 × 0.41 mm

■ Duty: 1/32

■ Display Color: Monochrome (White)



2. Module Classification information

| 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | 13 | 14 |
|---|---|---|--------|---|---|---|---|---|----|----|----|----|----|
| R | Е | Х | 012832 | Α | W | Р | Р | 3 | N | 0 | 0 | 0 | 00 |

| | 1 | | | | | |
|----|------------------|----------------|-----------------------|---------------------|---------|----------------|
| 1 | Brand : Raysta | r Opt | ronics Inc. | | | |
| 2 | E: OLED | | | | | |
| | | C: (| COB Character | | G : C | OB Graphic |
| 3 | Diaplay Type | X : (| COG | | H:C | OG + FR |
| 3 | Display Type | P:(| COG + FR + PCB | | T:T | Aβ |
| | | A : (| COG + PCB | | | / |
| 4 | Dot Matrix: 1: | 28*32 | 2 | | | |
| 5 | Series | | | | | |
| | | | A: Amber | R: Red | | C : Full Color |
| • | Facittia a Colon | | B: Blue | W: White | | |
| 6 | Emitting Color | | G: Green | Y: Yellow | | |
| | | | S: Sky Blue | X : Dual Color | | |
| 7 | Polarizer | | P: With Polarizer; | N: Without Polari | zer | |
| / | Polarizer | | A: Anti-glare Polar | izer | | |
| 8 | Display Mode | ! | P: Passive Matrix | ; N:Active Matri | X | |
| 9 | Driver Voltage | | 3:3.0~3.3V ; 5 | : 5.0V | | |
| 10 | Touch Panel | A | N: Without touch p | eanel; T: With touc | ch pane | el |
| | | | 0 : Standard | | | 200/ |
| | Product type | | 1 : Daylight Readal | | | |
| 11 | Product type | | 2: Transparent OL | | | |
| | | | 3: Flexible OLED (| FOLED) | | |
| | 7 | 7 | 4 : OLED Lighting | | | 0070 |
| | | | 0 : Standard | | | |
| 12 | Inspection Grad | 46 | 2 : B grade | | | |
| 12 | mapection Grat | J C | C: Automotive grad | | | |
| | 7 | | Y: Consumer grad | | | |
| 13 | Option | | 0 : Default ; F : ZIF | FPC; H: Hot ba | ar FPC | ; D : Demo Kit |
| 14 | Serial No. | | Serial number(00~2 | ZZ) | | 100000 |
| | 1 | | 1 | | | |



3.Interface Pin Function

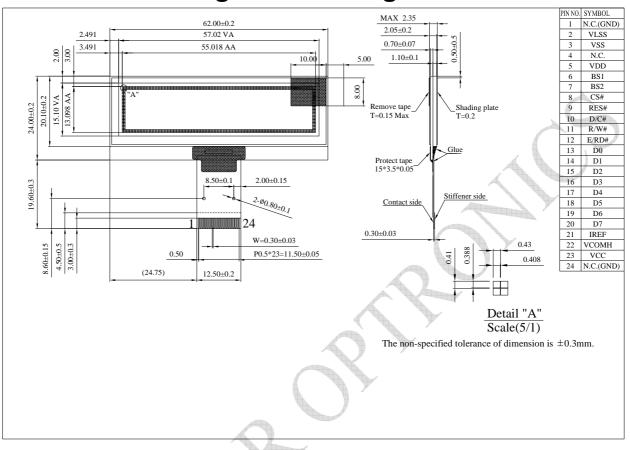
| No. | Symbol | Function | | | | | | |
|-----|-----------|--|--|--|--|--|--|--|
| 1 | N.C.(GND) | No connection | | | | | | |
| 2 | VLSS | This is an analog ground pin. It should be connected to VSS externally. | | | | | | |
| 3 | VSS | Ground. | | | | | | |
| 4 | N.C. | No connection | | | | | | |
| 5 | VDD | Power supply pin for core logic operation | | | | | | |
| 6 | BS1 | Communicating Protocol Select These pins are MCU interface selection input. See the following table: | | | | | | |
| 7 | BS2 | 68XX-parallel 80XX-parallel Serial I2C BS1 0 1 0 1 BS2 1 1 0 0 | | | | | | |
| 8 | CS# | This pin is the chip select input. (active LOW) | | | | | | |
| 9 | RES# | This pin is reset signal input. When the pin is LOW, initialization of the chip is executed. Keep this pin HIGH (i.e. connect to VDDIO) during normal operation. | | | | | | |
| 10 | D/C# | This is Data/Command control pin. When it is pulled HIGH (i.e. connect to VDDIO), the data at D[7:0] is treated as data. When it is pulled LOW, the data at D[7:0] will be transferred to the command register. In I2C mode, this pin acts as SA0 for slave address selection. | | | | | | |
| 11 | R/W# | This is read / write control input pin connecting to the MCU interface. When interfacing to a 6800-series microprocessor, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH (i.e. connect to VDDIO) and write mode when LOW. When 8080 interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled LOW and the chip is | | | | | | |
| | | selected. When serial interface is selected, this pin must be connected to VSS. | | | | | | |
| 10 | E/DD# | When interfacing to a 6800-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH (i.e. connect to VDDIO) and the chip is selected. | | | | | | |
| 12 | E/RD# | When connecting to an 8080-microprocessor, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected. When serial interface is selected, this pin must be connected to | | | | | | |



| | | VSS. |
|----|-----------|---|
| 13 | D0 | |
| 14 | D1 | These are 8-bit bi-directional data bus to be connected to the |
| 15 | D2 | microprocessor's data bus. |
| 16 | D3 | When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN and D2 |
| 17 | D4 | should be left opened. When I2C mode is selected, D2, D1 |
| 18 | D5 | should be field opened. When 120 mode is selected, b2, b1 |
| 19 | D6 | application and D0 is the serial clock input, SCL. |
| 20 | D7 | application and Bo to the sonal stock input, Col. |
| 21 | IREF | This is segment output current reference pin. A resistor should be connected between this pin and VSS to maintain the IREF current at 10uA. |
| 22 | VCOMH | The pin for COM signal deselected voltage level. A capacitor should be connected between this pin and VSS. |
| 23 | VCC | Power supply for panel driving voltage. This is also the most positive power voltage supply pin. |
| 24 | N.C.(GND) | No connection |

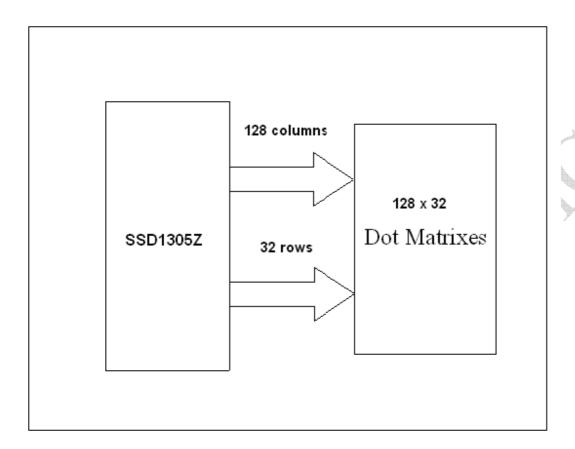


4.Contour Drawing & Block Diagram





FUNCTION BLOCK DIAGRAM



^{*}For more information, please refer to Application Note provided by Raystar Optronics.



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5.Absolute Maximum Ratings

| Parameter | Symbol | Min | Max | Unit | Notes |
|----------------------------|--------|------|-----|------|--------------|
| Supply Voltage for Logic | VDD | -0.3 | 4 | V | 1, 2 |
| Supply Voltage for Display | VCC | 0 | 15 | V | 1, 2 |
| Operating Temperature | TOP | -40 | +80 | C |) - |
| Storage Temperature | TSTG | -40 | +85 | C | - |

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate





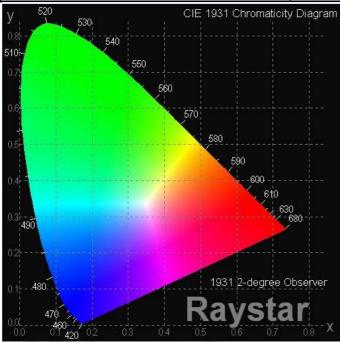
6.Electrical Characteristics

| Item | Symbol | Condition | Min | Тур | Max | Unit |
|-------------------------------------|--------|-----------|---------|---------|---------|--------|
| Supply Voltage for Logic | VDD | _ | 2.8 | 3.0 | 3.3 | V |
| Supply Voltage for Display | VCC | _ | 10 | 12 | 15 | \ \ |
| High Level Input | VIH | _ | 0.8×VDD | _ | VDD | V |
| Low Level Input | VIL | _ | 0 | - 4 | 0.2×VDD | V |
| High Level Output | VOH | _ | 0.9×VDD | \prec | VDD | V |
| Low Level Output | VOL | _ | 0 | _ | 0.1×VDD | V |
| 50% Check Board operatir Current | ng | VCC =12V | 22 | 23 | 25 | mA |



7. Optical Characteristics

| Item | Symbol | Condition | Min | Тур | Max | Unit |
|--------------------------|------------------|-----------|-----------|------|------|-------|
| View Angle | (V)θ | _ | 160 | _ | _ | deg |
| View / trigio | (Η)φ | _ | 160 — deg | | | |
| Contrast Ratio | CR | Dark | 2000:1 | - | | |
| Response Time | T rise | _ | _ | 10 | | μs |
| | T fall | _ | _ | 10 | | μs |
| Display with 50% check E | Board Brightness | | 100 | 120 | _ | cd/m2 |
| CIEx(White) | | (CIE1931) | 0.26 | 0.28 | 0.30 | _ |
| CIEy(White) | | (CIE1931) | 0.30 | 0.32 | 0.34 | _ |





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8.OLED Lifetime

| ITEM | Conditions | Min | Тур | Remark |
|------------------------|---|------------|-----|--------|
| Operating Life Time | Ta=25°C / Initial 50% check board brightness 100cd/m² | 20,000 Hrs | - | Note |

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.





9.Reliability

| Environmenta | I Test | | |
|---|--|---|---------------------|
| Test Item | Content of Test | Test Condition | Applicable Standard |
| High Temperature storage | Endurance test applying the high storage temperature for a long time. | 85℃ 240hrs | - (|
| Low Temperature storage | Endurance test applying the low storage temperature for a long time. | -40°ℂ 240hrs | |
| High Temperature Operation | Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time. | 80℃ 240hrs | |
| Low Temperature Operation | Endurance test applying the electric stress under low temperature for a long time. | -40℃ 240hrs | _ |
| High Temperature/ Humidity Storage | Endurance test applying the high temperature and high humidity storage for a long time. | 60°C,90%RH 240hrs | |
| High Temperature/ Humidity Operation | Endurance test applying the high temperature and high humidity Operation for a long time. | 60℃,90%RH 120hrs | |
| Temperature Cycle | Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min 1 cycle | -40°C/80°C 30 cycles | Es. |
| Mechanical Tes | st C | | |
| Vibration test | Endurance test applying the vibration during transportation and using. | Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z | - 20 |
| Others | 7 | <u>, </u> | |
| Static electricity test | Endurance test applying the electric stress to the terminal. | Air Discharge model ±4kv,10 times | |

^{***} Supply voltage for OLED system =Operating voltage at 25 $^{\circ}\mathrm{C}$



Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5℃; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



10.Inspection specification

| NO | Item | Criterion | | | AQL | | |
|----|---------------------|--|---------------|---|-------------------|------|--|
| 01 | Electrical | 1.1 Missing vertical, horizontal segment, segment contrast | | | | | |
| | Testing | defect. | | | | | |
| | | 1.2 Missing chara | | or icon. | | 2 | |
| | | 1.3 Display malfu | | | | | |
| | | 1.4 No function o | | | | 0.65 | |
| | | | | exceeds product s | pecifications. | 0.00 | |
| | | 1.6 OLED viewing angle defect. | | |) ` | | |
| | | 1.7 Mixed product types. | | | | | |
| | | 1.8 Contrast defe | ect. | | | | |
| 02 | Black or | O.4 White and block and an disclay < 0.05 and a disclay < 1 | | | | | |
| 02 | white | 2.1 White and black spots on display \leq 0.25mm, no more than three white or black spots present. | | | | | |
| | spots on | | • | ore than two spot | s or lines within | | |
| | OLED | 3mm. | , ou. 110 111 | oro triair two opot | o or miles within | 2.5 | |
| | (display | | | | | | |
| | only) | | | | | | |
| 03 | OLED | 3.1 Round type: | | | | | |
| | black | following drawing |) | SIZE | Acceptable Q | | |
| | spots, | $\Phi = (x + y) / 2$ | | | TY | | |
| | white | ,X | | Ф≦0.10 | Accept no | | |
| | spots, | <u>_</u> | | 0.10 | dense | 2.5 | |
| | contamina tion | • - | Y | 0.10 < | 2 | 2.5 | |
| | (non-displ | Ť | | Ф≦0.20 | | | |
| | ay) | | | 0.20< | 1 | | |
| | (3) | | | Ф≦0.25 | | | |
| | | | | 0.25 < Ф | 0 | | |
| | | 3.2 Line type : (As following drawing) | | 9 | | | |
| | A | (. | Length | Width | Acceptable Q TY | | |
| | | $\sim 1 \frac{w}{w}$ | | W≦0.02 | Accept no dense | 0.5 | |
| | | →ı , н← | L≦3.0 | 0.02 <w≤0.03< td=""><td>2</td><td>2.5</td></w≤0.03<> | 2 | 2.5 | |
| | | | L≦2.5 | 0.03 <w \u220e90.05<="" td=""><td>2</td><td></td></w> | 2 | | |
| | | | | 0.05 <w< td=""><td>As round type</td><td></td></w<> | As round type | | |
| 04 | Polarizer | | | | | | |
| 0. | bubbles If ju sp to | If bubbles are vis | ible. | Size Φ | Acceptable Q TY | | |
| | | judge using black | • | Φ≦0.20 | Accept no dense | | |
| | | specifications, not e to find, must check i specify direction. | • | 0.20<Φ≦0.50 | 3 | 2.5 | |
| | | | | 0.50 < Φ≦1.00 | 2 | 2.5 | |
| | | | <u> </u> | 1.00 < Φ <u>1.00</u> | 0 | -00 | |
| | | | Total Q TY | 3 / 00 00 | | | |
| | Ì | | | ן וטומו ע דו | | | |



| NO | Item | Criterion | | | AQL |
|---|---------------|--|--|------------------------|-----|
| 05 | Scratches | Follow NO.3 OLED b | lack spots, white spo | ts, contamination | |
| | | Symbols Define: x: Chip length | y: Chip width z: 0 t: Glass thickness a | Chip thickness | |
| | Chipped glass | 6.1 General glass chi 6.1.1 Chip on panel s | • | ween panels: | 5 |
| | | | N. C. | | |
| | | z: Chip thickness | y: Chip width | x: Chip length | |
| | | Z≦1/2t | Not over viewing | x≦1/8a | |
| 06 | | | area Not exceed 1/3k | x≦1/8a | 2.5 |
| | | ⊙ If there are 2 or mo | pre chips, x is total ler | ngth of each chip. | |
| | | W.F. | 3500 | | 101 |
| | A | z: Chip thickness | y: Chip width | x: Chip length | |
| | | Z≦1/2t | Not over viewing area | x≦1/8a | |
| | | 1/2t < z ≤ 2t | Not exceed 1/3k | x≦1/8a | |
| ⊙ If there are 2 or more chips, x is the total length of each chip. | | | | I length of each chip. | |



| NO | Item | Criterion | AQL | | |
|----|-------------------------------|---|-----|--|--|
| | | Symbols: | | | |
| | | x: Chip length y: Chip width z: Chip thickness | | | |
| | | k: Seal width t: Glass thickness a: OLED side length | | | |
| | L: Electrode pad length | | | | |
| | | 6.2 Protrusion over terminal: | | | |
| | 6.2.1 Chip on electrode pad : | | | | |
| | | and T | | | |
| | | | | | |
| | | D Z |) ` | | |
| | | | | | |
| | | | | | |
| | | V A V X | | | |
| | | y: Chip width x: Chip length z: Chip thickness | | | |
| | | $y \le 0.5$ mm $x \le 1/8$ a $0 < z \le t$ | | | |
| | | 6.2.2 Non-conductive portion: | | | |
| | | | | | |
| | | | | | |
| 00 | Glass | | 2.5 | | |
| 06 | crack | A2 V | 2.5 | | |
| | | | | | |
| | | X | | | |
| | | y: Chip width x: Chip length z: Chip | | | |
| | | thickness | | | |
| | | $y \le L$ $x \le 1/8a$ $0 < z \le t$ | | | |
| | | ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO | | | |
| | | must remain and be inspected according to electrode terminal | | | |
| | | specifications. | | | |
| | | ⊙ If the product will be heat sealed by the customer, the alignment | | | |
| | | mark not be damaged. | | | |
| | | 6.2.3 Substrate protuberance and internal crack. | | | |
| | T T | y: width x: length | | | |
| A | | $y \le 1/3L$ $x \le a$ | | | |
| | Andrew | y N | | | |
| | | | | | |
| | | | | | |
| | | 1600 | :03 | | |
| | | | | | |



| NO | Item | Criterion | AQL |
|----|--------------------|---|---|
| 07 | Cracked glass | The OLED with extensive crack is not acceptable. | 2.5 |
| 08 | Backlight elements | 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. | 0.65 2.5 0.65 |
| 09 | Bezel | 9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications. | 2.5 0.65 |
| 10 | PCB、COB | 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. | 2.5 2.5 0.65 2.5 2.5 0.65 2.5 |
| 11 | Soldering | 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. | 2.5 2.5 2.5 0.65 |



| NO | Item | Criterion | AQL |
|----|------------|--|------|
| | | 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. | 2.5 |
| | | 12.2 No cracks on interface pin (OLB) of TCP. | 0.65 |
| | | 12.3 No contamination, solder residue or solder balls on | 2.5 |
| | | product. | 2.5 |
| | | 12.4 The IC on the TCP may not be damaged, circuits. | 2.5 |
| | | 12.5 The uppermost edge of the protective strip on the | |
| 12 | General | interface pin must be present or look as if it cause the interface pin to sever. | 2.5 |
| 12 | appearance | 12.6 The residual rosin or tin oil of soldering (component or | 2.5 |
| | | chip component) is not burned into brown or black color. | 0.65 |
| | | 12.7 Sealant on top of the ITO circuit has not hardened. | 0.65 |
| | | 12.8 Pin type must match type in specification sheet. | 0.65 |
| | | 12.9 OLED pin loose or missing pins. | |
| | | 12.10 Product packaging must the same as specified on packaging specification sheet. | 0.65 |
| | | 12.11 Product dimension and structure must conform to | |
| | | product specification sheet. | |
| | | | |





| Check Item | Classification | Criteria |
|--|----------------|-------------------------------------|
| No Display | Major | |
| Missing Line | Major | |
| Pixel Short | Major | |
| Darker Short | Major | |
| Wrong Display | Major | |
| Un-uniform B/A x 100% < 70% A/C x 100% < 70% | Major | A Normal B Dark Fixel B Light Fixel |



11.Precautions in use of OLED Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time.
- (10) Raystar has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11) Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)

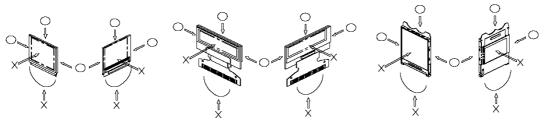
11.1 Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
- * Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.





- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

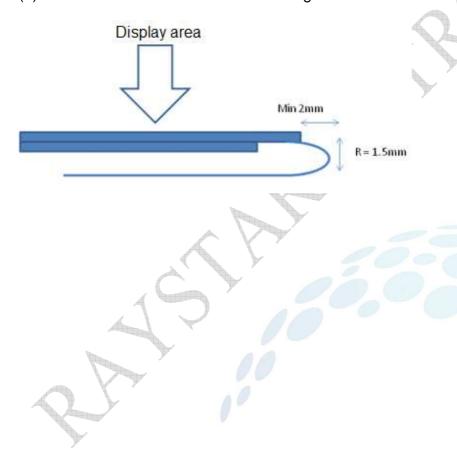
11.2 Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0℃) environments.(We recommend you to store these modules in the packaged state when they were shipped from Raystar Optronics Inc. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.



11.3 Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.
- (8) The limitation of FPC and Film bending.





| raye. I | | | | |
|---------------------------------------|-------------|-------|--|--|
| Module Sample Estimate Feedback Sheet | | | | |
| Module Number: | | | | |
| | | | | |
| 1 · Panel Specification : | | | | |
| 1. Panel Type: | □ Pass | □NG , | | |
| 2. Numbers of Pixel: | □ Pass | □NG , | | |
| 3. View Area: | □ Pass | □NG , | | |
| 4. Active Area: | □ Pass | □NG , | | |
| 5.Emitting Color: | □ Pass | □NG , | | |
| 6.Uniformity: | □Pass | □NG , | | |
| 7.Operating | □ Pass | □NG , | | |
| Temperature : | | Y Y | | |
| 8.Storage Temperature: | □ Pass | □NG , | | |
| 9.Others: | • | | | |
| 2 · Mechanical Specificati | <u>on</u> : | | | |
| 1. PCB Size : | □Pass | □NG , | | |
| 2.Frame Size : | □Pass | □NG , | | |
| 3.Materal of Frame: | □Pass | □NG , | | |
| 4.Connector Position: | □Pass | □NG , | | |
| 5.Fix Hole Position: | □Pass | □NG , | | |
| 6. Thickness of PCB: | □Pass | □NG , | | |
| 7. Height of Frame to | □Pass | □NG , | | |
| PCB: | | | | |
| 8.Height of Module: | □Pass | □NG , | | |
| 9.Others: | □Pass | □NG , | | |
| 3 · Relative Hole Size : | | | | |
| 1.Pitch of Connector: | □Pass | □NG , | | |
| 2.Hole size of | □Pass | □NG , | | |
| Connector: | | | | |
| 3.Mounting Hole size : □Pass | | □NG , | | |
| 4.Mounting Hole Type : □Pass | | □NG , | | |
| 5.Others : □Pass | | □NG , | | |

>> Go to page 2 <<



Page: 2 **Module Number**: 4 · Electronic Characteristics of Module: □NG ,____ □Pass 1.Input Voltage: 2.Supply Current: □NG ,_____ □Pass 3.Driving Voltage for □Pass □NG , OLED: 4.Contrast for OLED: □Pass □NG ,____ 5.Negative Voltage □Pass □NG , Output: 6.Interface Function: □NG , □Pass □NG ,__ 7.ESD test: □Pass 8.Others: □NG ,_ □Pass 5 \ Summary : Sales signature :

Date: /

Customer Signature :